

Feature

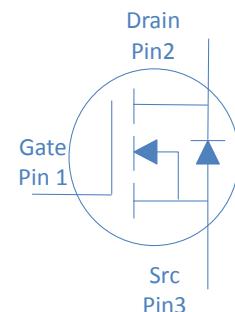
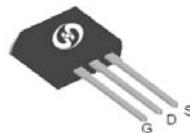
- ◇ High Speed Power Switching, Logic Level
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free, Halogen Free

60V N-Ch Power MOSFET

V_{DS}	60	V
$R_{DS(on),typ}$	$V_{GS}=10V$	4.1 mΩ
$R_{DS(on),typ}$	$V_{GS}=4.5V$	5.6 mΩ
I_D (Silicon Limited)	105	A

Application

- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ DC/DC in Telecoms and Industrial

TO-262


Part Number	Package	Marking
HGW053N06SL	TO-262	GW053N06SL

Absolute Maximum Ratings at $T_j=25^\circ C$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^\circ C$	105	A
		$T_C=100^\circ C$	74	
Drain to Source Voltage	V_{DS}	-	60	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	250	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.4mH, T_C=25^\circ C$	80	mJ
Power Dissipation	P_D	$T_C=25^\circ C$	125	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 175	°C

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	46	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	1.2	°C/W

Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit	
			min	typ	max		
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	60	-	-	V	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	1.0	1.6	2.4		
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=60\text{V}, T_j=25^\circ\text{C}$	-	-	1	μA	
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=60\text{V}, T_j=100^\circ\text{C}$	-	-	100		
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA	
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=20\text{A}$	TO-262	-	4.1	5.3	m Ω
		$V_{\text{GS}}=4.5\text{V}, I_D=20\text{A}$	TO-262	-	5.6	7.5	m Ω
Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_D=20\text{A}$	-	48	-	S	
Gate Resistance	R_G	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	1.5	-	Ω	

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=30\text{V}, f=1\text{MHz}$	-	2274	-	pF
Output Capacitance	C_{oss}		-	793	-	
Reverse Transfer Capacitance	C_{rss}		-	35	-	
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DD}}=30\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	36	-	nC
Total Gate Charge	$Q_g(4.5\text{V})$		-	18	-	
Gate to Source Charge	Q_{gs}		-	4.5	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	7.5	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=30\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega,$	-	11	-	ns
Rise time	t_r		-	7	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	35	-	
Fall Time	t_f		-	10	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=30\text{V}, I_F=20\text{A}, dI_F/dt=300\text{A}/\mu\text{s}$	-	30	-	ns
Reverse Recovery Charge	Q_{rr}		-	53	-	nC

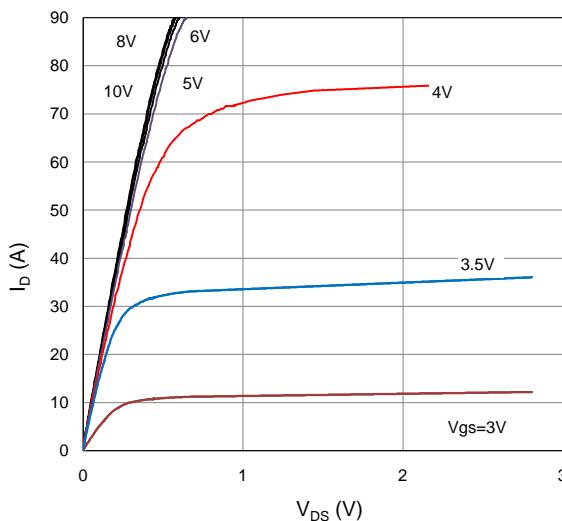
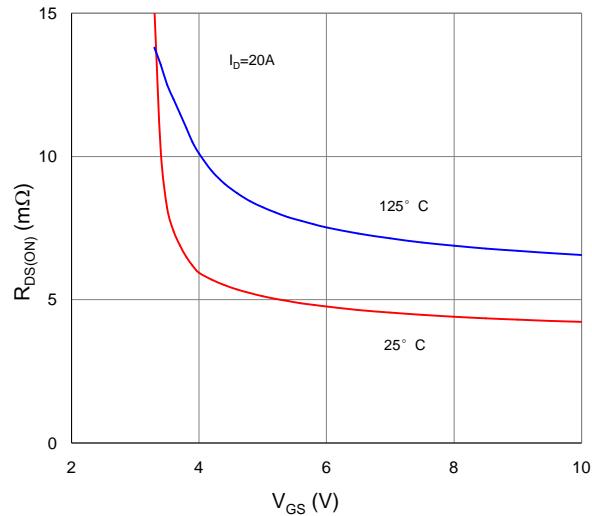
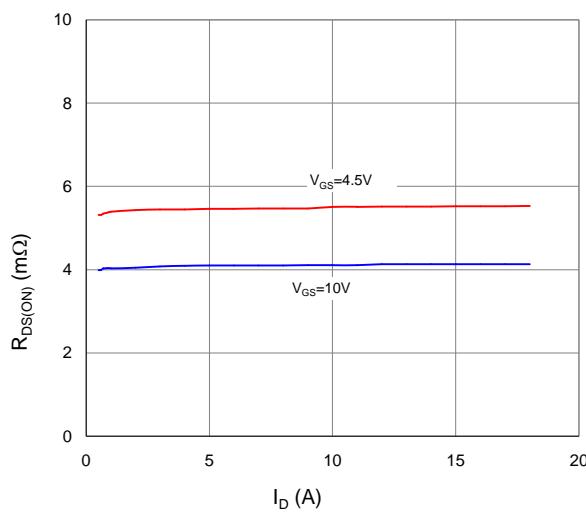
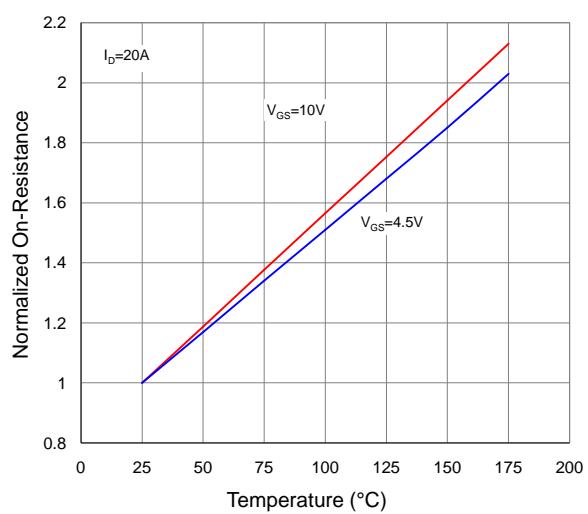
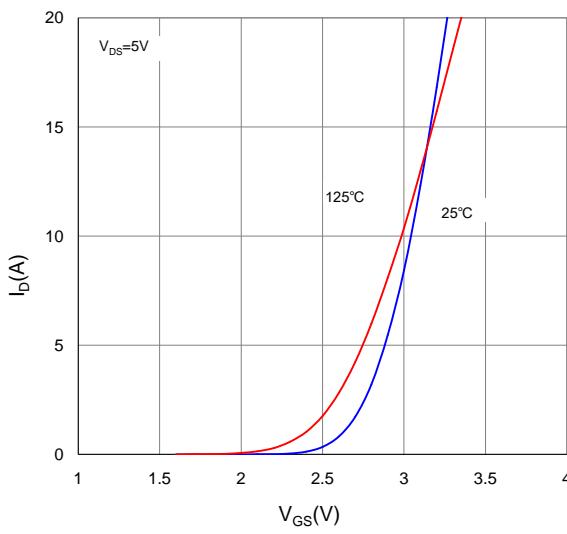
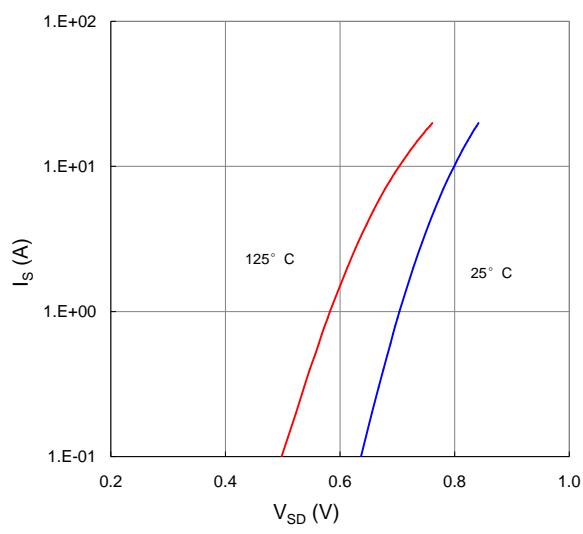
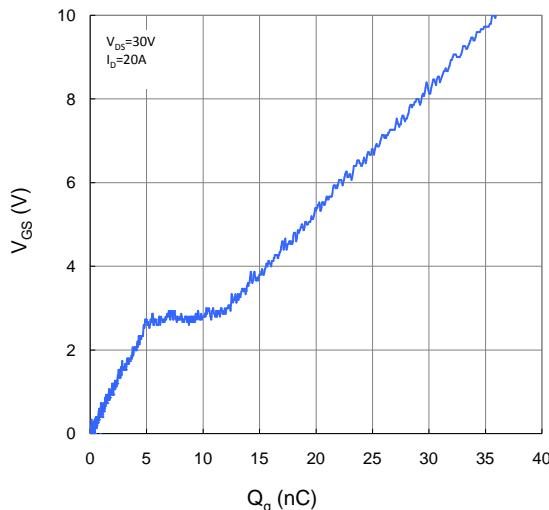
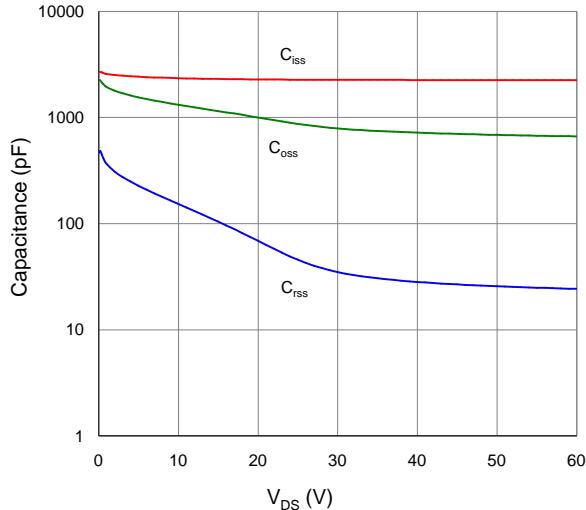
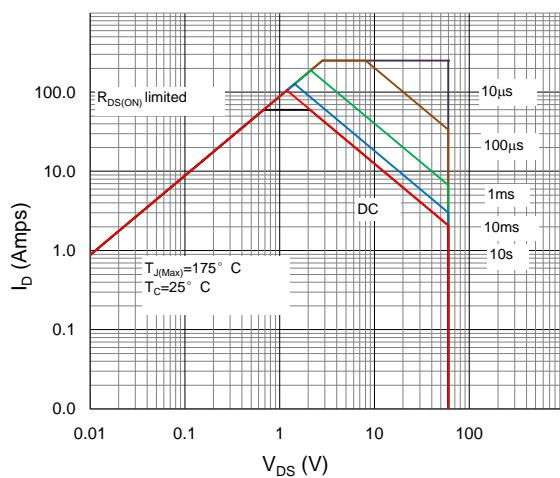
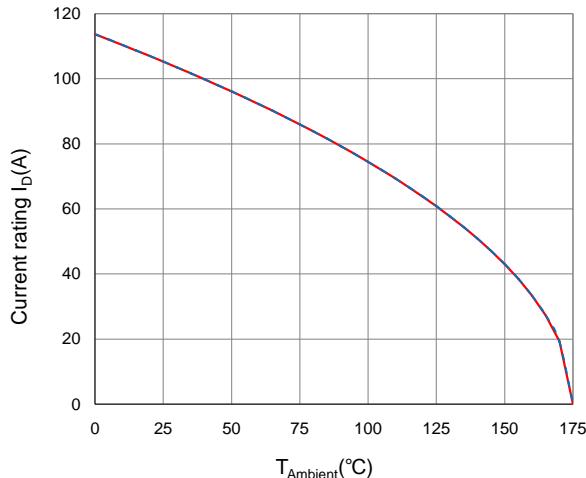
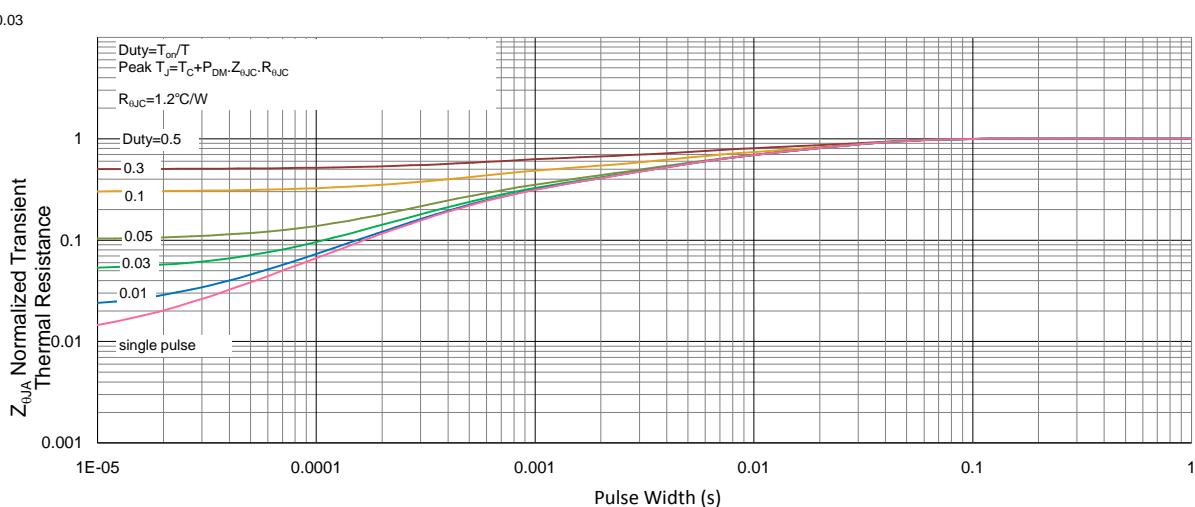
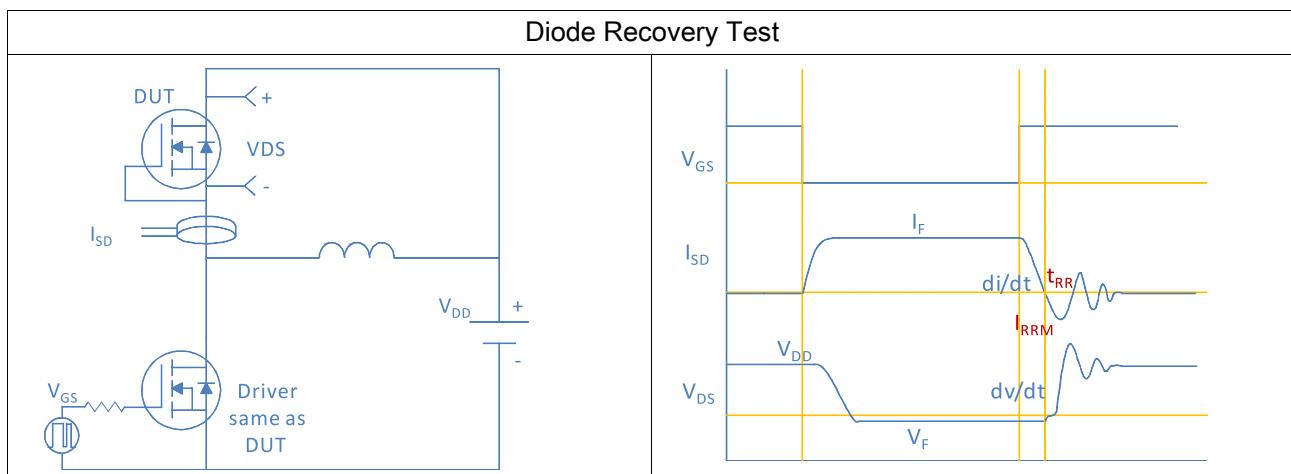
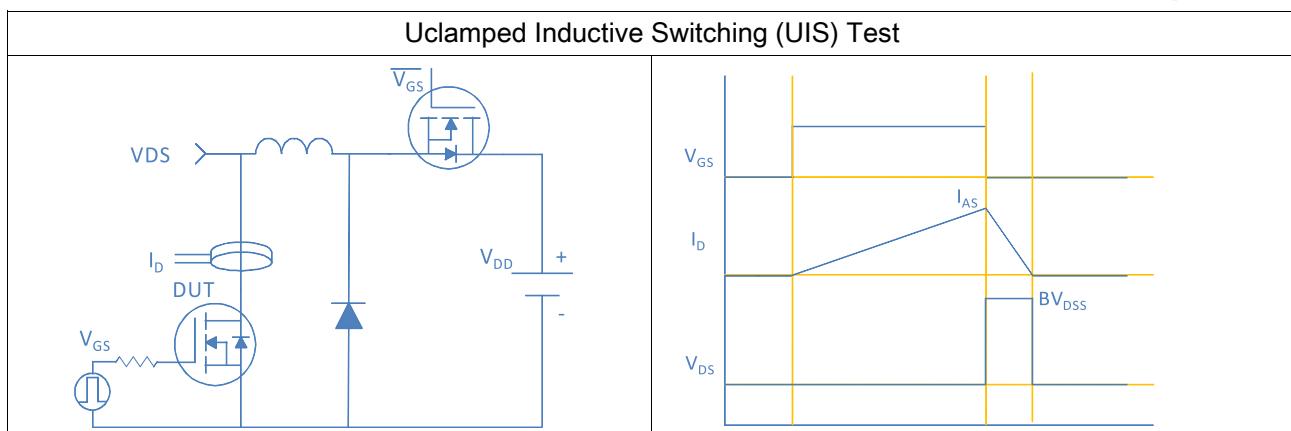
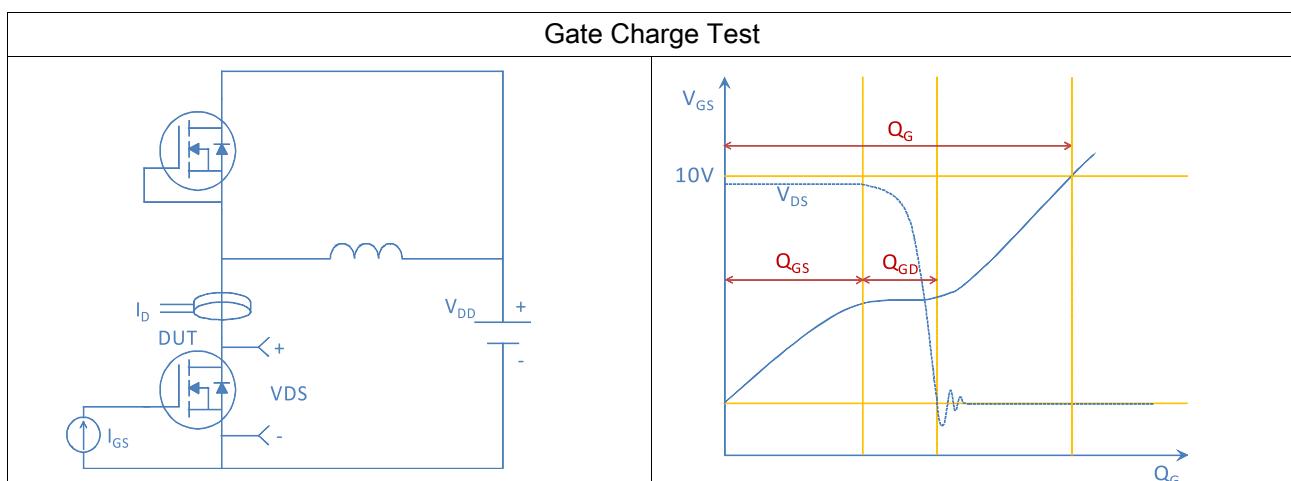
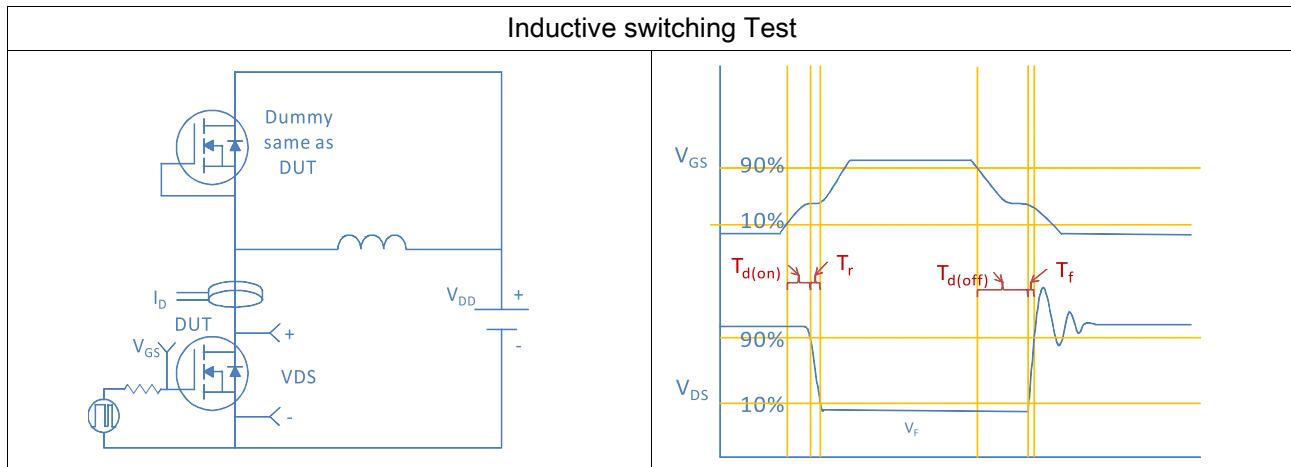
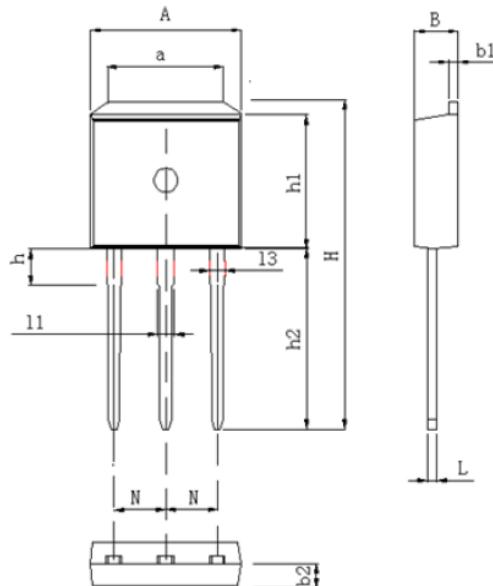
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient




Package Outline
TO-262, 3 leads


Unit: mm

DIM	MILLIMETERS
A	9.98±0.2
a	7.4±0.4
B	4.5±0.2
b1	1.3±0.05
b2	2.4±0.2
H	23.9±0.3
h	3.1±0.2
h1	9.16±0.2
h2	13.2±0.2
L	0.5±0.1
l1	1.3±0.1
l2	0.8±0.1
N	2.45±0.1